

FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

DESCRIPTION

This 12-bit to 24-bit registered bus exchanger is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16270 is used in applications in which data must be transferred from a narrow high-speed bus to a wide lower-frequency bus.

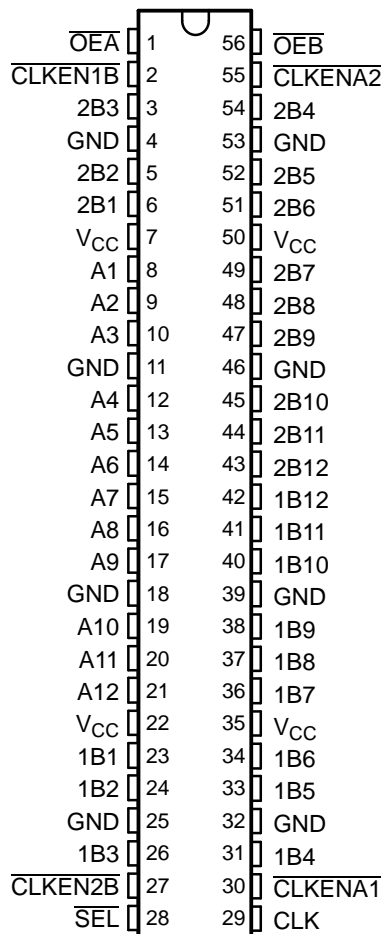
The device provides synchronous data exchange between the two ports. Data is stored in the internal registers on the low-to-high transition of the clock (CLK) input when the appropriate \overline{CLKEN} inputs are low. The select (\overline{SEL}) line selects 1B or 2B data for the A outputs. For data transfer in the A-to-B direction, a two-stage pipeline is provided in the A-to-1B path, with a single storage register in the A-to-2B path. Proper control of the \overline{CLKENA} inputs allows two sequential 12-bit words to be presented synchronously as a 24-bit word on the B port. Data flow is controlled by the active-low output enables (\overline{OEA} , \overline{OEB}). The control terminals are registered to synchronize the bus-direction changes with CLK.

To ensure the high-impedance state during power up or power down, a clock pulse should be applied as soon as possible, and \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. Due to \overline{OE} being routed through a register, the active state of the outputs cannot be determined prior to the arrival of the first clock pulse.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16270 is characterized for operation from -40°C to 85°C.

DGG OR DL PACKAGE
(TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SN74ALVCH16270
12-BIT TO 24-BIT REGISTERED BUS EXCHANGER
WITH 3-STATE OUTPUTS

SCES028G—JULY 1995—REVISED AUGUST 2004

FUNCTION TABLES

OUTPUT ENABLE

INPUTS			OUTPUTS	
CLK	$\overline{OE\bar{A}}$	$\overline{OE\bar{B}}$	A	1B, 2B
↑	H	H	Z	Z
↑	H	L	Z	Active
↑	L	H	Active	Z
↑	L	L	Active	Active

A-TO-B STORAGE ($\overline{OE\bar{B}} = L$)

INPUTS				OUTPUTS	
$\overline{CLKEN\bar{A}1}$	$\overline{CLKEN\bar{A}2}$	CLK	A	1B	2B
L	H	X	X	1B ₀ ⁽¹⁾	2B ₀ ⁽¹⁾
L	H	X	X	1B ₀ ⁽¹⁾	2B ₀ ⁽¹⁾
L	L	↑	L	L ⁽²⁾	L
L	L	↑	H	H ⁽²⁾	H
H	L	↑	L	1B ₀ ⁽¹⁾	L
H	L	↑	H	1B ₀ ⁽¹⁾	H
H	H	X	X	1B ₀ ⁽¹⁾	2B ₀ ⁽¹⁾

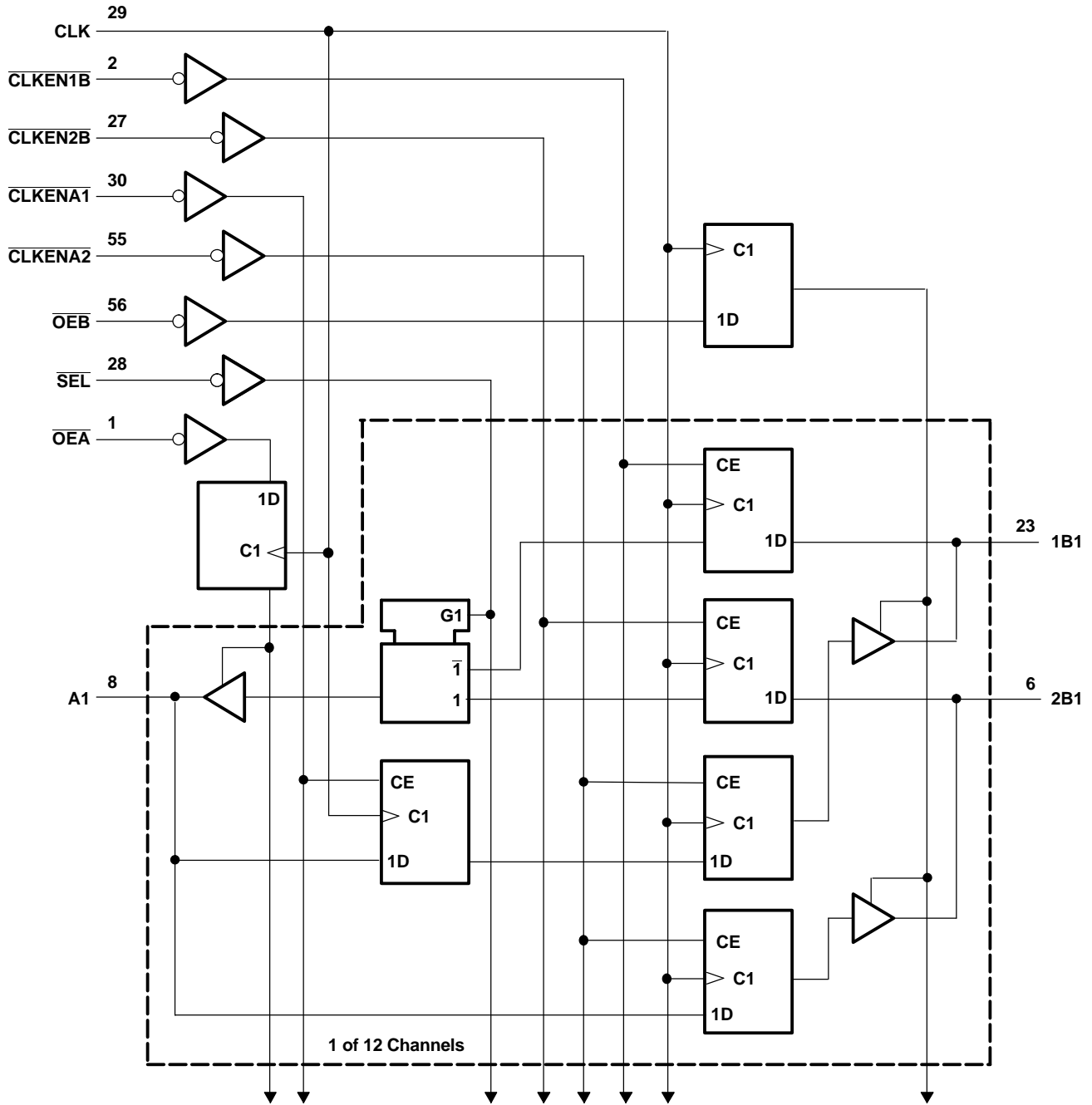
- (1) Output level before the indicated steady-state input conditions were established
- (2) Two CLK edges are needed to propagate data.

B-TO-A STORAGE ($\overline{OE\bar{A}} = L$)

INPUTS					OUTPUT	
$\overline{CLKEN1\bar{B}}$	$\overline{CLKEN2\bar{B}}$	CLK	\overline{SEL}	1B	2B	A
H	X	X	H	X	X	A ₀ ⁽¹⁾
X	H	X	L	X	X	A ₀ ⁽¹⁾
L	X	↑	H	L	X	L
L	X	↑	H	H	X	H
X	L	↑	L	X	L	L
X	L	↑	L	X	H	H

- (1) Output level before the indicated steady-state input conditions were established

LOGIC DIAGRAM (POSITIVE LOGIC)



SN74ALVCH16270

12-BIT TO 24-BIT REGISTERED BUS EXCHANGER WITH 3-STATE OUTPUTS

SCES028G–JULY 1995–REVISED AUGUST 2004

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	-0.5	4.6	V
V _I	Input voltage range	Except I/O ports ⁽²⁾		V
		-0.5	4.6	
V _O	Output voltage range ⁽²⁾⁽³⁾	I/O ports ⁽²⁾⁽³⁾		V
		-0.5	V _{CC} + 0.5	
I _{IK}	Input clamp current	V _I < 0		-50
I _{OK}	Output clamp current	V _O < 0		-50
I _O	Continuous output current			±50
	Continuous current through each V _{CC} or GND			±100
θ _{JA}	Package thermal impedance ⁽⁴⁾	DGG package		81
		DL package		74
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	1.65		V
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V		V
		V _{CC} = 2.3 V to 2.7 V		
		V _{CC} = 2.7 V to 3.6 V		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V		V
		V _{CC} = 2.3 V to 2.7 V		
		V _{CC} = 2.7 V to 3.6 V		
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V		mA
		V _{CC} = 2.3 V		
		V _{CC} = 2.7 V		
		V _{CC} = 3 V		
I _{OL}	Low-level output current	V _{CC} = 1.65 V		mA
		V _{CC} = 2.3 V		
		V _{CC} = 2.7 V		
		V _{CC} = 3 V		
Δt/Δv	Input transition rise or fall rate	10		ns/V
T _A	Operating free-air temperature	-40	85	°C

- (1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2			V
	I _{OH} = -4 mA	1.65 V	1.2			
	I _{OH} = -6 mA	2.3 V	2			
	I _{OH} = -12 mA	2.3 V	1.7			
		2.7 V	2.2			
		3 V	2.4			
I _{OH} = -24 mA	3 V	2				
V _{OL}	I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	V
	I _{OL} = 4 mA	1.65 V			0.45	
	I _{OL} = 6 mA	2.3 V			0.4	
	I _{OL} = 12 mA	2.3 V			0.7	
		2.7 V			0.4	
	I _{OL} = 24 mA	3 V			0.55	
I _I	V _I = V _{CC} or GND	3.6 V			±5	μA
I _{I(hold)}	V _I = 0.58 V	1.65 V	25			μA
	V _I = 1.07 V	1.65 V	-25			
	V _I = 0.7 V	2.3 V	45			
	V _I = 1.7 V	2.3 V	-45			
	V _I = 0.8 V	3 V	75			
	V _I = 2 V	3 V	-75			
	V _I = 0 to 3.6 V ⁽²⁾	3.6 V			±500	
I _{OZ} ⁽³⁾	V _O = V _{CC} or GND	3.6 V			±10	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V			40	μA
ΔI _{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	3.5		pF
C _{io}	A or B ports	V _O = V _{CC} or GND	3.3 V	9		pF

 (1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

 (3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

SN74ALVCH16270

12-BIT TO 24-BIT REGISTERED BUS EXCHANGER WITH 3-STATE OUTPUTS

SCES028G—JULY 1995—REVISED AUGUST 2004

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f_{clock}	Clock frequency	(1)		150		150		150		MHz	
t_w	Pulse duration, CLK high or low	(1)		3.3		3.3		3.3		ns	
t_{su}	Setup time	A data before CLK \uparrow		(1)		4.1		3.8		3.1	
		B data before CLK \uparrow		(1)		0.9		1.2		0.9	
		$\overline{\text{CLKENA1}}$ or $\overline{\text{CLKENA2}}$ before CLK \uparrow		(1)		3.5		3.2		2.7	
		$\overline{\text{CLKEN1B}}$ or $\overline{\text{CLKEN2B}}$ before CLK \uparrow		(1)		3.4		3		2.6	
		$\overline{\text{OE}}$ data before CLK \uparrow		(1)		4.4		3.9		3.2	
t_h	Hold time	A data after CLK \uparrow		(1)		0		0		0.2	
		B data after CLK \uparrow		(1)		1.4		1		1.7	
		$\overline{\text{CLKENA1}}$ or $\overline{\text{CLKENA2}}$ after CLK \uparrow		(1)		0		0.1		0.3	
		$\overline{\text{CLKEN1B}}$ or $\overline{\text{CLKEN2B}}$ after CLK \uparrow		(1)		0		0		0.6	
		$\overline{\text{OE}}$ after CLK \uparrow		(1)		0		0		0.1	

(1) This information was not available at the time of publication.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			(1)		150		150		150		MHz
t_{pd}	CLK	B	(1)		1.5 5.9		5.8		1.1 5.1		ns
		A	(1)		1.2 5.4		5.4		1 4.7		
	$\overline{\text{SEL}}$	A	(1)		1.4 6.2		6.4		1 5.5		
t_{en}	CLK	A or B	(1)		1.5 7		6.8		1 6		ns
t_{dis}	CLK	A or B	(1)		1.9 7.2		6.5		1.1 5.8		ns

(1) This information was not available at the time of publication.

OPERATING CHARACTERISTICS

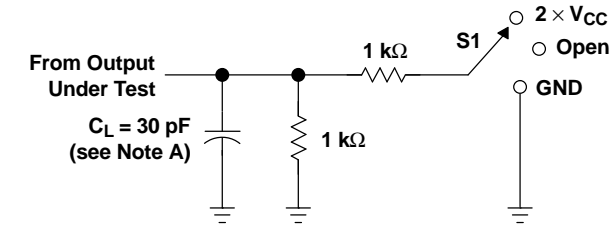
$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	Outputs enabled	(1)	87	120	pF
		Outputs disabled	(1)	80.5	118	

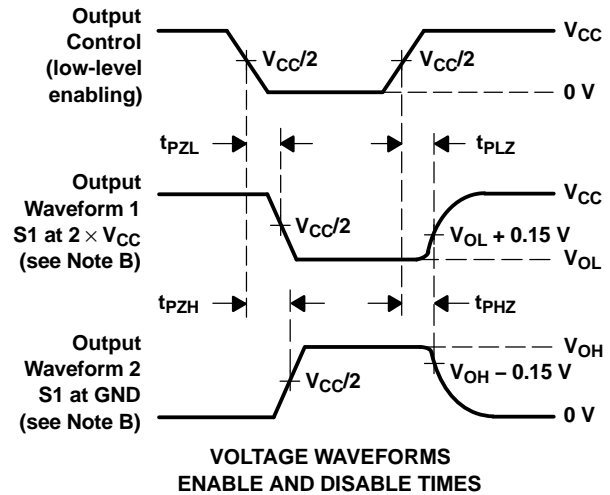
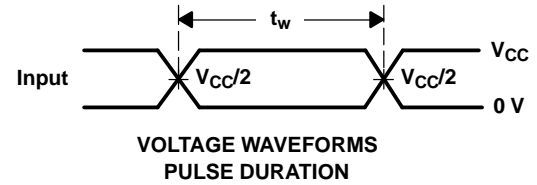
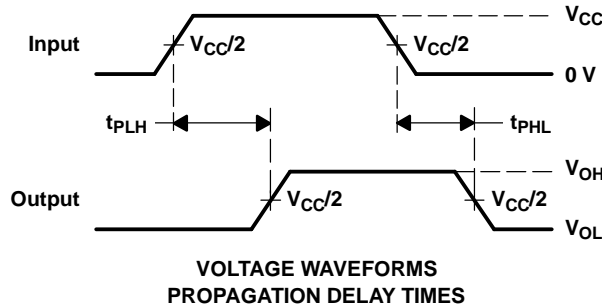
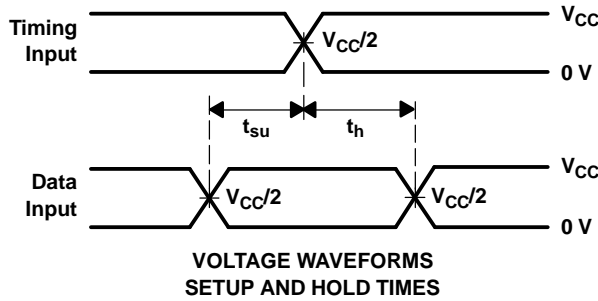
(1) This information was not available at the time of publication.

PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 1.8\text{ V}$



LOAD CIRCUIT



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .

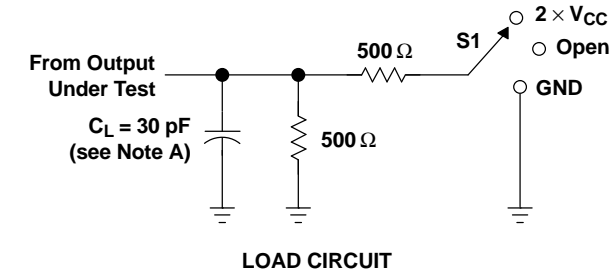
Figure 1. Load Circuit and Voltage Waveforms

SN74ALVCH16270 12-BIT TO 24-BIT REGISTERED BUS EXCHANGER WITH 3-STATE OUTPUTS

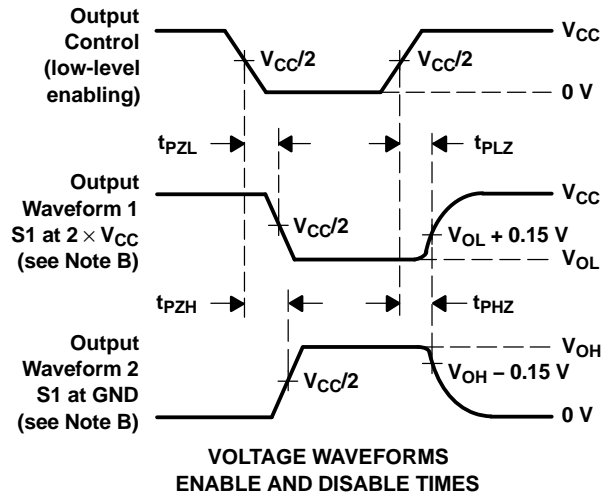
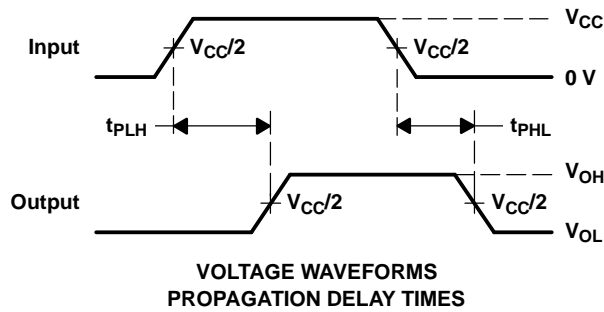
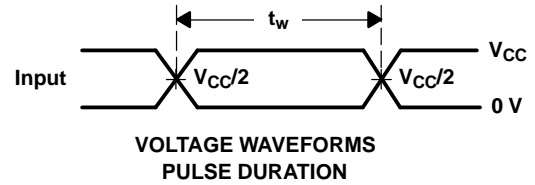
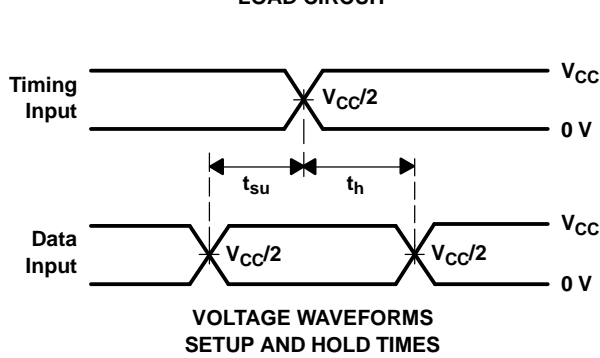
SCES028G—JULY 1995—REVISED AUGUST 2004

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$



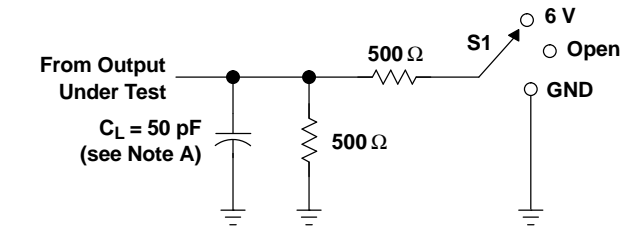
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PLH} and t_{PHL} are the same as t_{pd} .

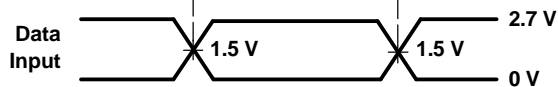
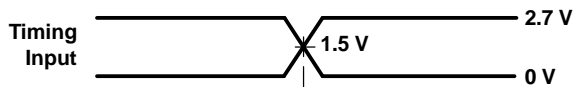
Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.7\text{ V AND } 3.3\text{ V} \pm 0.3\text{ V}$

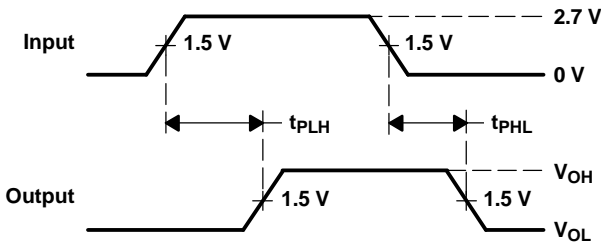


LOAD CIRCUIT

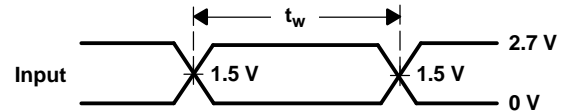
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



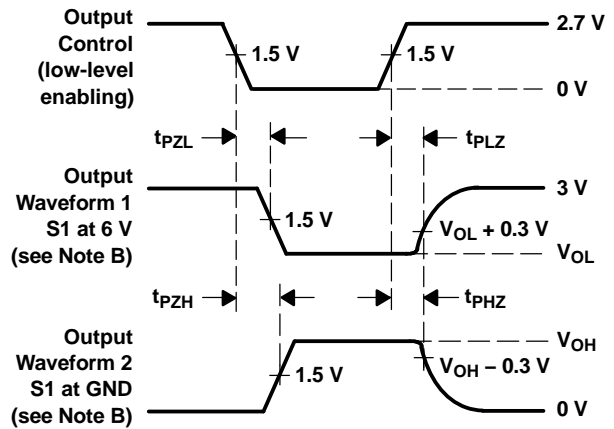
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVCH16270DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16270DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16270DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16270DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16270DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16270DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16270DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

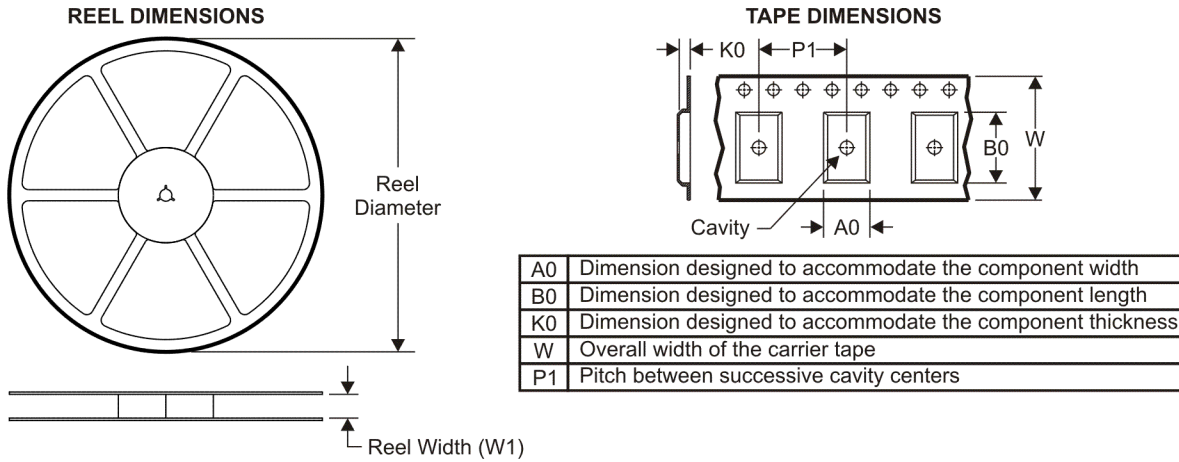
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

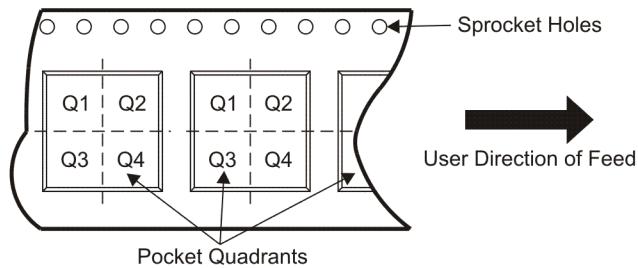
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TAPE AND REEL INFORMATION



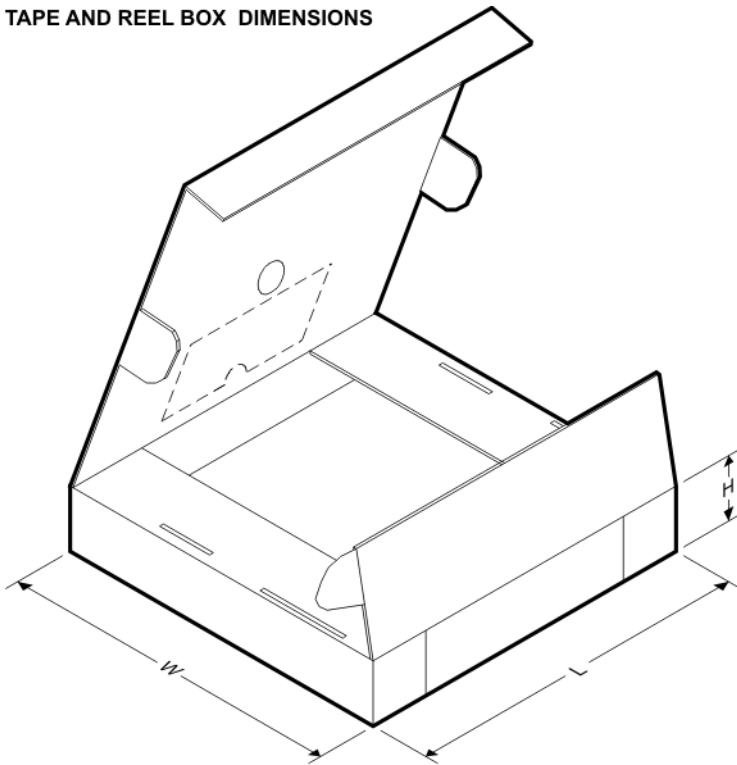
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16270DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ALVCH16270DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



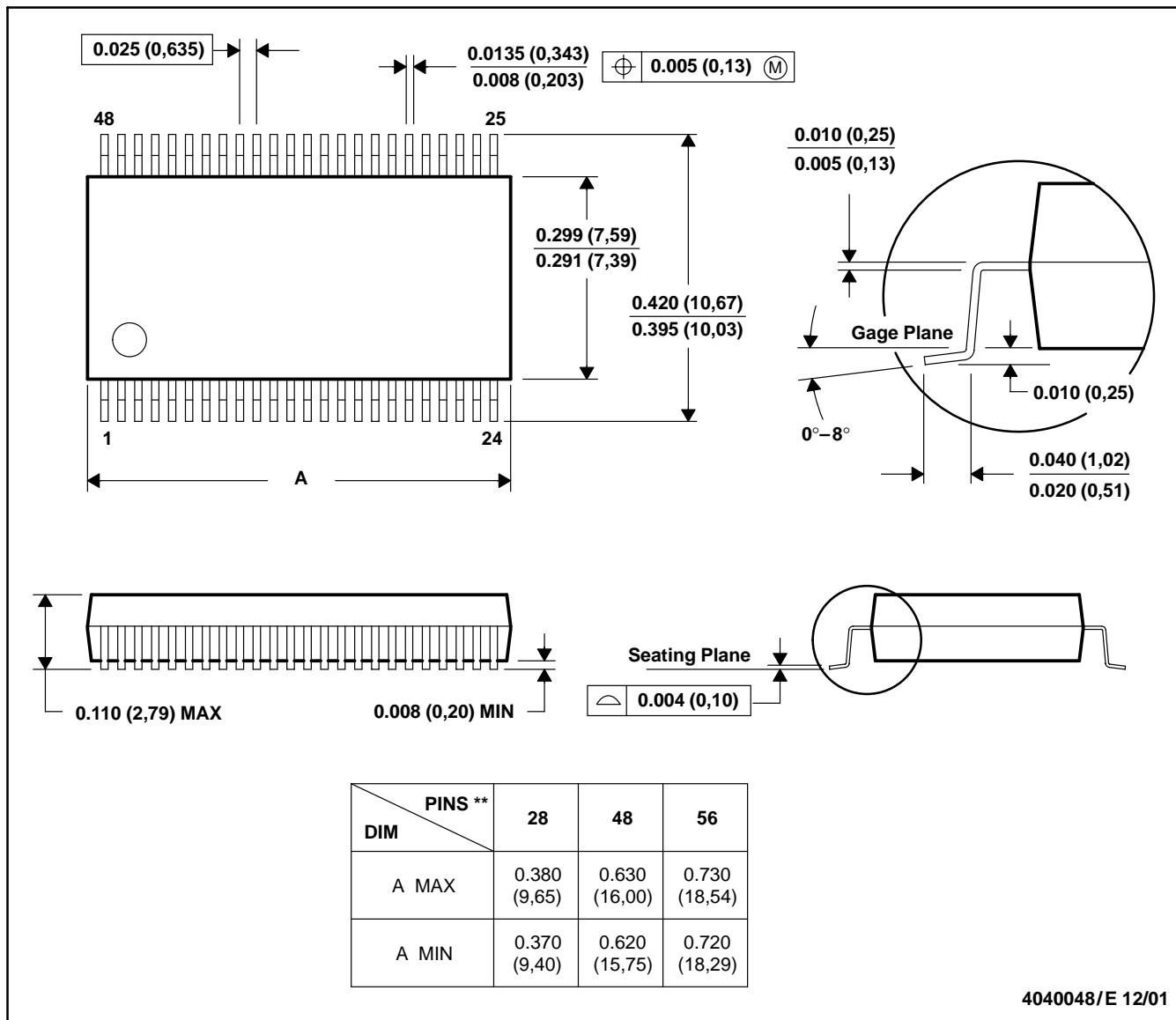
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16270DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ALVCH16270DLR	SSOP	DL	56	1000	346.0	346.0	49.0

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

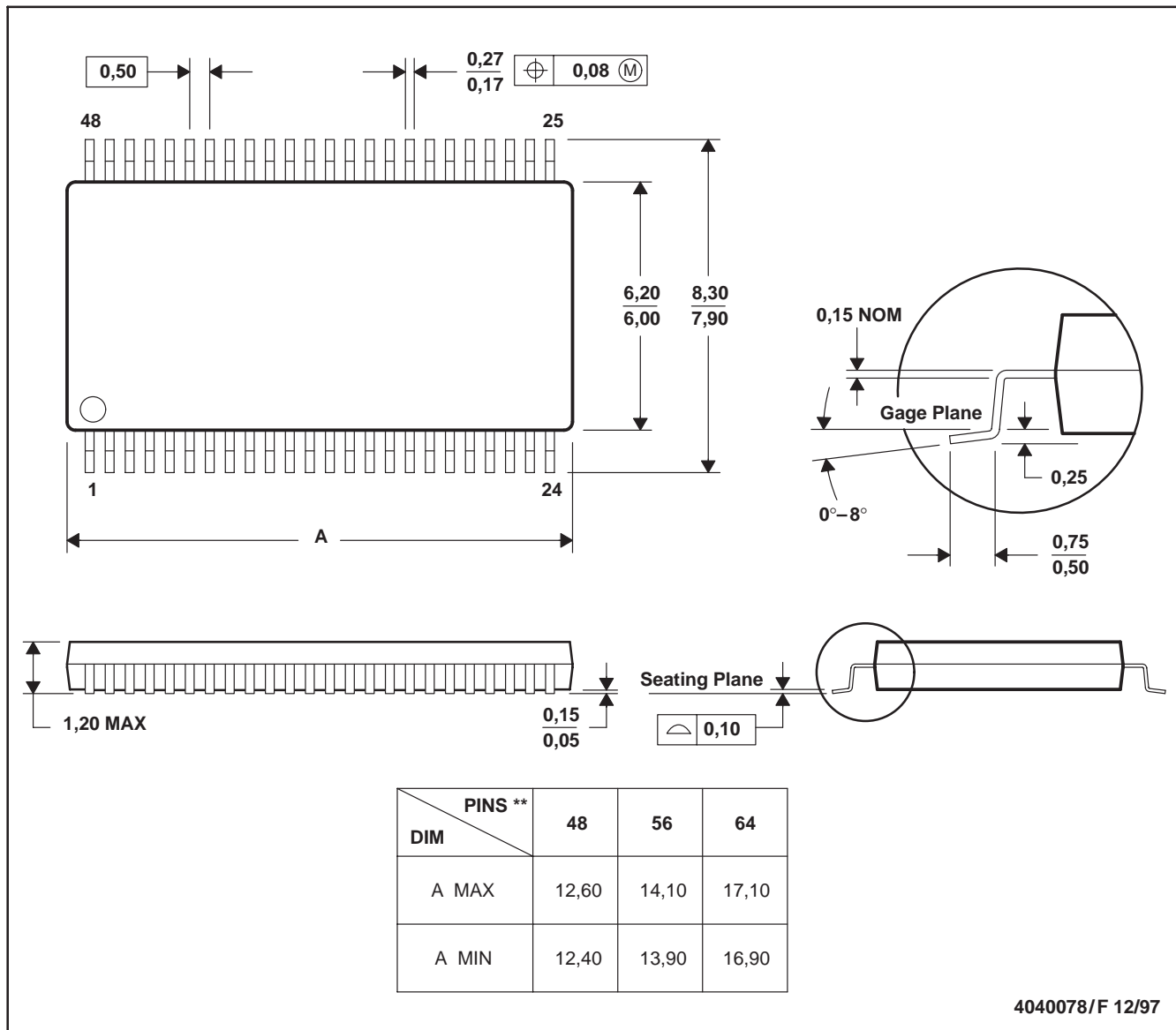


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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